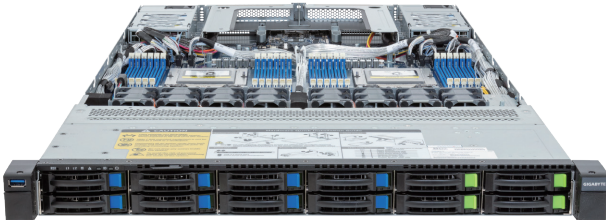


R183-Z94-AAD2

Rack Server - 1U DP 12-Bay NVMe/SATA



Key Features

- Dual AMD EPYC™ 9005/9004 Series Processors
- 12-Channel DDR5 RDIMM, 24 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 8 x 2.5" SATA/SAS-4 hot-swap bays
- 3 x M.2 slots with PCIe Gen3 x4 and x2 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 1600W 80 PLUS Platinum redundant power supply

Application

Networking, Hybrid/Private Cloud Server...

Specification

Dimensions 1U (W438 x H43.5 x D815 mm)

Motherboard MZ93-FS1

CPU AMD EPYC™ 9005 Series Processors
AMD EPYC™ 9004 Series Processors
Dual processors, cTDP up to 300W
- At ambient 30°C, cTDP up to 400W

Sock 2 x LGA 6096 (Socket SP5)

Chipset System on Chip

Memory 12-Channel DDR5 RDIMM, 24 x DIMMs
[EPYC 9005] Up to 6000 MT/s
[EPYC 9004] Up to 4800 MT/s

LAN 2 x 1Gb/s LAN (1 x Intel® I350-AM2) - Supports NCSI function
1 x 10/100/1000 Mbps Management LAN

Video Integrated in ASPEED® AST2600 - 1 x Mini-DP

Storage Front hot-swap:
4 x 2.5" Gen5 NVMe/SATA/SAS-4
8 x 2.5" SATA/SAS-4
*SAS card is required to support SAS drives.

Internal M.2:
2 x M.2 (2280/22110), PCIe Gen3 x4
1 x M.2 (2280/22110), PCIe Gen3 x2

RAID Require RAID add-in cards

Expansion Slots 2 x FHHL PCIe Gen5 x16 slots
2 x OCP NIC 3.0 PCIe Gen5 x16 slots - Supports NCSI function

I/O Ports Front: 1 x USB 3.2 Gen1
Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN

Backplane Board Speed and bandwidth:
PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s

Security Modules 1 x TPM header with SPI interface
- Optional TPM2.0 kit: CTM010

Power Supply Dual 1600W 80 PLUS Platinum redundant power supply
AC Input: 100-240V

System Management ASPEED® AST2600 Baseboard Management Controller
GIGABYTE Management Console web interface

OS Support Windows Server, Red Hat Enterprise Linux server, Ubuntu,
SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor

System Fans 8 x 40x40x56mm (32,000rpm)

Operating Properties Operating temperature: 10°C to 35°C
Operating humidity: 8%-80% (non-condensing)
Non-operating temperature: -40°C to 60°C
Non-operating humidity: 20%-95% (non-condensing)

Packaging Content 1 x R183-Z94-AAD2, 2 x CPU heatsinks,
1 x Mini-DP to D-Sub cable, 1 x 2-Section Rail kit
Packaging Dimensions: 1045 x 595 x 249 mm

Part Numbers Barebone package: 6NR183Z94DR000ACD2*
Optional parts:
- 3-Section Rail kit (Supports CMA): 25HB2-A56121-K0R
- Cable Management Arm: 25HB1-R18300-K0R
- RMA packaging: 6NR183Z94SR-RMA-A100



Learn more at <https://www.GIGABYTE.com/enterprise>

* All specifications are subject to change without notice. Please visit our website for the latest information.
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